

BM3301 – 1313 Module

Wi-Fi 6 and BLE 5.4 Wireless Module - Powered by TI CC3301

Datasheet

V0.9

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1 Introduction

BM3301 – 1313 is a 2.4-GHz Wi-Fi6 and Bluetooth Low Energy wireless module based on TI's 10th-generation connectivity combo chip CC3301, which is based upon proven technology. This Module is ideal for use in cost-sensitive embedded application with a Linux or RTOS host running TCP/IP. This Module is an ideal platform for developing wireless communication product solutions.

Features

- Wi-Fi 6
 - 2.4 GHz, 20 MHz, single spatial stream
 - MAC, baseband, and RF transceiver with support for IEEE 802.11 b/g/n/ax
 - Target wake time (TWT), OFDMA, MU-MIMO (Downlink), Basic Service Set Coloring, and trigger frame for improved efficiency
 - Hardware-based encryption and decryption using supporting WPA2 and WPA3
 - Excellent interoperability
 - Support for 4-bits SDIO or SPI host interfaces
- Bluetooth Low Energy 5.4
 - LE Coded PHYs (Long Range), LE 2M PHY (High Speed) and Advertising Extension
 - Host controller interface (HCI) transport with option for UART or shared SDIO
- Security
 - Secured host interface
 - Firmware authentication
 - Anti-rollback protection
- Application throughput up to 50 Mbps
- 3-wire or 1-wire PTA for external coexistence with additional 2.4-GHz radios (for example, Thread or Zigbee)
- Multirole support (for example, concurrent STA and AP) to connect with Wi-Fi devices on different RF channels (Wi-Fi networks)
- 1 integrated antenna port (supporting Wi-Fi and Bluetooth Low Energy coexistence)
- Compact footprint and pins with SMT package
- Integrated 2.4-GHz PA for complete wireless solution with up to +20dBm output power
- Using an IPEX Gen4 socket to connect an external antenna (ex: Rubber ducky antenna, PCB antenna, FPC antenna)
- Operation temperature: -40°C to 85°C
- Operation humidity: 10%~ 85%

Application

- Internet of Things (IoT)
- Multimedia
- Home Electronics
- Home Application and White Goods

- Industrial and Home Automation
- Smart Gateway and Metering
- Video Conferencing
- Video Camera and Security

This product specification includes a detailed description of the BM3301 – 1x1x Module's performance and functions. For the latest firmware, product updates or errata, please contact Seeed Studio.

2 Description

BM3301 – 1313 Module is embedded with TI CC3301, which is very suitable for the design of various embedded devices. The module, as seen in below diagram, comprise of:

- 40Mhz XTAL
- Bandpass filter
- Decoupling capacitors

2.1 Pin Diagram



Figure 2-3. BM3301-1313 Module Pin arrangement

2.2 Pin Attributes

Table 2-1. BM3301-1313 Module pinout

Number	Name	Voltage Level	Type	Description
1	GND		-	Ground
2	NC		-	Not connected
3	IRQ_BLE	1.8V	-	IRQ_BLE to Host (in shared SDIO mode) (Reuse as working mode configuration)

4	SWCLK	1.8	I	Serial Wire Debug CLK
5	SWDIO	1.8V	I/O	Serial Wire Debug DIN/DOOUT
6	SDIO_CMD	1.8V	I/O	SDIO_CMD_WL (SPI_DIN)
7	GND		-	Ground
8	SDIO_CLK	1.8V	I	SDIO_CLK (SPI_CLK)
9	GND		-	Ground
10	SDIO_D0	1.8V	I/O	SDIO_D0_WL (SPI_DOUT)
11	SDIO_D1	1.8V	I/O	SDIO_D1_WL
12	SDIO_D2	1.8V	I/O	SDIO_D2_WL
13	SDIO_D3	1.8V	I/O	SDIO_D3_WL (SPI_CS)
14	IRQ_WL	1.8V	I/O	IRQ_WL to Host (Reuse as working mode configuration)
15	GND		-	Ground
16	GND		-	Ground
17	GND		-	Ground
18	ANT2/NC		-	Not connected
19	GND		-	Ground
20	GND		-	Ground
21	NC		-	Not connected
22	NC		-	Not connected
23	GND		-	Ground
24	GND		-	Ground
25	NC		-	Not connected
26	Fast_CLK_REQ	1.8V	O	Fast clock request from the device
27	ANT_SEL	1.8V	I/O	Default antenna select control line
28	GND		-	Ground
29	GND		-	Ground
30	GND		-	Ground
31	GND		-	Ground
32	ANT1_2.4GHz		ANT	WLAN and Bluetooth Low Energy RF Port
33	GND		-	Ground
34	GND		-	Ground
35	GND		-	Ground
36	Slow_CLK	1.8V	I	External Slow Clock Input
37	GND		-	Ground
38	VIO/1V8	1.8V	Power	1.8V Power Supply
39	GND		-	Ground

40	RESET	1.8V	I	Disable or enable the Module (Active low).
41	NC		-	Not connected
42	Logger	1.8V	O	UART TX Debug Logger (Reuse as working mode configuration)
43	NC		-	Not connected
44	GND		-	Ground
45	GND		-	Ground
46	VBAT/3V3	3.3V	Power	3.3V Power Input
47	VBAT/3V3	3.3V	Power	3.3V Power Input
48	GND		-	Ground
49	GND		-	Ground
50	UART_RTS	1.8V	O	Device RTS signal – flow control for BLE HCI
51	UART_CTS	1.8V	I	Device CTS signal – flow control for BLE HCI
52	UART_TX	1.8V	O	UART TX for BLE HCI
53	UART_RX	1.8V	I	UART RX for BLE HCI
54	GND		-	Ground
55	GND		-	Ground
56	COEX_REQ	1.8V	I	External Coexistence Interface -Request
57	COEX_GRANT	1.8V	O	External Coexistence Interface -Grant
58	COEX_PRIORITY	1.8V	I	External Coexistence Interface -Priority
59	GND		-	Ground
60	NC		-	Not connected
61	GND		-	Ground
62	NC		-	Not connected
63	GND		-	Ground
64	GND		-	Ground
G1-G36	GND		-	Ground

3 Electrical characteristics

3.1 Absolute Maximum Ratings

Reaching or exceeding the maximum ratings listed in the table below can cause equipment damage.

Table 3-1. Absolute Maximum Ratings

Parameter	Description	min	max	unit
VBAT/3V3	1313-Module 3.3V Supply Voltage	-0.5	4.2	V

VIO/1V8	1313-Module 1.8V Supply & IO Voltage	-0.5	2.1	V
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3.2 Normal working conditions

Table 3-2. Recommended Operating Conditions

Parameter	Description	min	TYP	max	unit
VBAT/3V3	1313-Module 3.3V Supply Voltage	3.0	3.3	3.6	V
VIO/1V8	1313-Module 1.8V Supply & IO Voltage	1.62	1.8	1.98	V
V _{IO}	1313-Module IO voltage	1.62	1.8	1.98	V
T _{op}	Operation temperature	-40		+85	°C

3.3 Electrical Characteristics

Table 3-3. BM3301-1x1x Module Electrical Characteristics

Parameter	Description	Test Condition	min	TYP	max	unit
V _{IH}	High level input voltage		0.65 x V _{IO}		V _{IO}	V
V _{IL}	Low level input voltage		0		0.35 x V _{IO}	V
V _{OH}	High level output voltage	At 4mA	V _{IO} – 0.45		V _{IO}	V
V _{OL}	Low level output voltage	At 4mA	0		0.45	V

3.4 Module specifications

Table 3-4. BM3301-1313 Module features

ITEMs	Parameter		Specifications				Unit
Structure	Size	1313-Module	13.3(W) x 13.4(L) x 2(H)Max				mm
	Package	1313-Module	100 pins LGA Module				
	Sleep current	1313-Module	200 (TBD)				uA
			15(TBD)				
	Operation current (Transmitter)	1313-Module	3.3V	Avg.	Peak	Conditions	mA
				250	290	20.2dBm 6 OFDM	
			1.8V	250		20dBm BLE 1M Channel 4	
				105	170	20.2dBm 6 OFDM	
				105		20dBm BLE 1M Channel 4	
	Operation current (Receiver)		TBD @ Wi-Fi Continous Receive				mA
			TBD @ Bluetooth Scan				
			TBD @ Wi-Fi Scan				
	TX Output power(Max)		20 @ 11ax SU ER MCS0				dBm
16 @ BLE 20dBm 1M Channel 4							
Sensitivity		Wi-Fi@20-MHz bandwidth. At <10% PER limit				dBm	

		Condi tions	min	type	max	
		1 DSS	-		-	
		2 DSS	-		-	

ITEMs	Descriptions
Peripheral Interface	SDIO 3.0
	SPI
	UART
	Coexistence
	SWD

4 Timing and Switching Characteristics

4.1 Power Supply Sequencing

For proper operation of the device, perform the recommended power-up sequencing as follows:

1. All supplies (VBAT, VIO) must be available before Reset is released.
2. For an external slow clock, ensure that the clock is stable before Reset is deasserted (high).
3. The Reset pin should be held low for 10 us after stabilization of the external power supplies.

4.2 Clocking Specifications

A slow clock running at 32.768 kHz for low power modes

4.2.1 Slow Clock Generated Internally

In order to minimize external components, the slow clock can be generated by an internal oscillator. However, this clock is less accurate and consumes more power than sourcing the slow clock externally. For this scenario the Slow_CLK pin should be left not connected.

4.2.2 Slow Clock Using an External Oscillator

For optimal power consumption, the slow clock can be generated externally by an oscillator or sourced from elsewhere in the system. The external source must meet the requirements listed below. This clock should be fed into the BMCC3301-1313 pin Slow_CLK and should be stable before nReset is deasserted and device is enabled.

4.2.2.1 External Slow Clock Requirement

Parameter	Description	min	TYP	max	Unit
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Input slow clock frequency	Square wave		32768		Hz
Frequency accuracy	Initial + temperature + aging			±250	ppm
Input Duty cycle		30	50	70	%
Rise and fall time	10% to 90% (rise) and 90% to 10% (fall) of digital signal level			100	ns
V _{IL} (Input low level)		0		0.35 x V _{IO}	V
V _{IH} (Input high level)		0.65 x V _{IO}		1.95	V
Input impedance		1			MΩ
Input capacitance				5	pF

5 Application information

5.1 Package information

5.1.1 BM3301-1313 Module Package information

Figure 5-1-1. BM3301-1313 Module Package Outline Drawing

5.2 Land Pattern

The following figure shows the recommended pad dimensions.

5.2.1 BM3301-1313 Module Recommended Pad Dimensions

Figure 5-2-1. BM3301-1313 Module Recommended Pad Dimensions

5.3 Reference design based on BM3301-1x1x Module

Considering different application scenarios, we provide two different reference designs.

5.3.1 BM3301-1313 Module Block Diagram

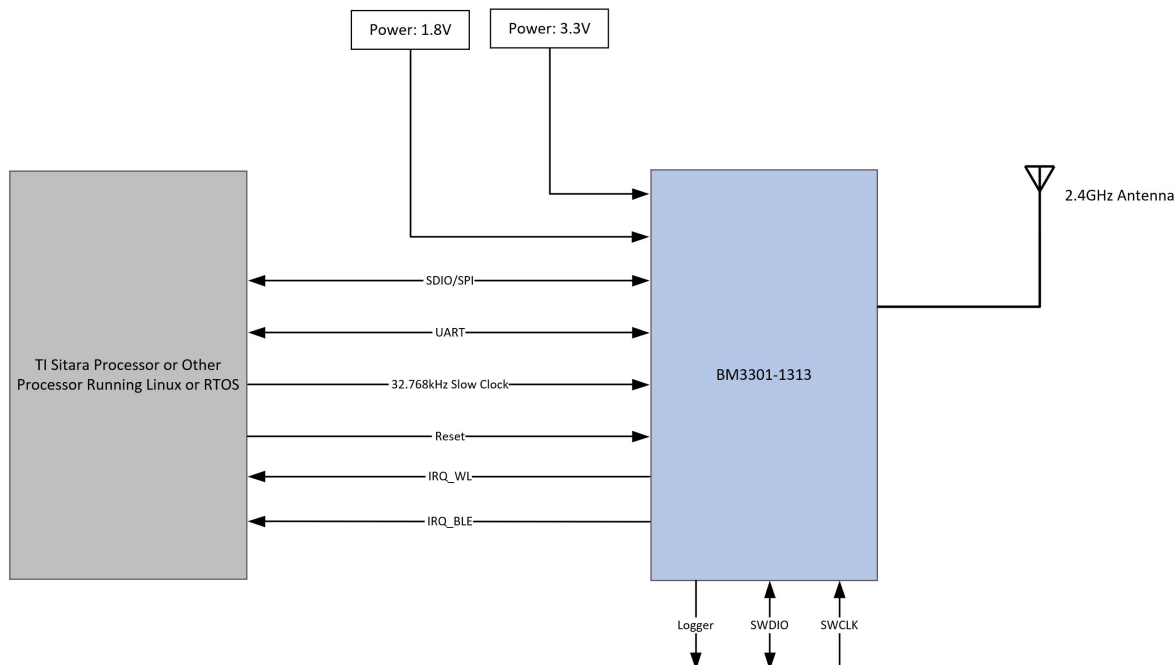


Figure 5-3-1. BM3301-1313 Module System Block Diagram

Notes:

1. IRQ_WL, IRQ_BLE, Logger are used to configure the working mode. IRQ_WL, IRQ_BLE need to be pulled down, Logger needs to be pulled up.
2. IRQ_WL, IRQ_BLE, Logger already have internal pull-up or pull-down resistors. External resistors are not required, but it is recommended to reserve positions for resistors.
3. SWDIO, do not add pull-down resistor.
4. SWCLK, do not add pull-up resistor.

5.3.2 SDIO lines

Due to the size of the module, the length of SDIO lines is not equal within the module, and it is necessary to compensate for the unequal length lines in your design.

The length of each SDIO lines of BM3301-1313 Module

- SDIO_CLK: 215.67 mil
- SDIO_CMD: 200.84 mil
- SDIO_D0: 119.37 mil
- SDIO_D1: 170.47 mil
- SDIO_D2: 214.72 mil
- SDIO_D3: 276.10 mil

6 Ordering information

Technical Support:

Sales:

Table 5 Ordering Information

Part Number	Package size (mm)	IPEX GEN4
BM3301-1313 Module	13(W) x 13(L) x 2.1(H)max	No

7 Reversion

V0.9 2023-05-25 Draft release

8 FCC

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This modular complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter. This modular must be installed and operated with a minimum distance of 20 cm between the radiator and user body.

If the FCC identification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following:

“Contains Transmitter Module FCC ID:Z4T-BM3301-1313”

The module is limited to OEM installation ONLY

The OEM integrators is responsible for ensuring that the end-user has no manual instructions to remove or install module

The module is limited to installation in mobile or fixed applications, according to Part 2.1091(b)

The separate approval is required for all other operating configurations, including portable configurations with respect to configurations

The devices must be installed and used in strict accordance with the manufacturer's instructions as described in the user documentation that comes with the product.

IC

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

(1) This device may not cause interference.

(2) This device must accept any interference, including interference that may cause undesired operation of the device.

L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence.

L'exploitation est autorisée aux deux conditions suivantes :

(1) L'appareil ne doit pas produire de brouillage;

(2) L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter. Cet émetteur ne doit pas être colocalisé ou fonctionner en conjonction avec une autre antenne ou un autre émetteur.

The device meets the exemption from the routine evaluation limits in section 2.5 of RSS-102 and compliance with RSS-102 RF exposure, users can obtain Canadian information on RF exposure and compliance. This equipment should be installed and operated with a minimum distance of 20 centimeters between the radiator and your body.

Le dispositif rencontre l'exemption des limites courantes d'évaluation dans la section 2.5 de RSS 102 et la conformité à l'exposition de RSS-102 rf, utilisateurs peut obtenir l'information canadienne sur l'exposition et la conformité de rf. Cet émetteur ne doit pas être Co-placé ou ne fonctionnant en même temps qu'aucune autre antenne ou émetteur. Cet équipement devrait être installé et actionné avec une distance minimum de 20 centimètres entre le radiateur et votre corps.

Please notice that if the ISED certification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains IC: 21046-BM33011313" any similar wording that expresses the same meaning may be used.

Veuillez noter que si le numéro de certification ISDE n'est pas visible lorsque le module est installé à l'intérieur d'un autre dispositif, alors l'extérieur du dispositif dans lequel le module est installé doit également afficher une étiquette se référant au module fermé. Cette étiquette extérieure peut utiliser des libellés tels que: «contient IC: 21046-BM33011313» toute formulation similaire qui exprime la même signification peut être utilisée.

Antenna information

Antenna Type	Antenna Gain
Rod antenna	2.81 dBi
PCB antenna	2.87 dBi

Trace antenna designs: Not applicable.

Type d'antenne	Max Gain d' antenne
Rod antenna	2.81 dBi
PCB antenna	2.87 dBi